

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) An encapsulation for an organic electronic component, characterized in that the component, encapsulated in a dimensionally stable capsule, is at least partially covered with a protective film.
2. (Original) The encapsulation as in claim 1, wherein said dimensionally stable capsule is glued to the substrate.
3. (Currently Amended) The encapsulation as in ~~either of claims~~ claim 1 or 2, wherein the entire exterior of the component is covered with a protective film.
4. (Currently Amended) The encapsulation as in ~~one of the preceding claims~~ claim 1, wherein said protective film includes at least one thin-barrier film.
5. (Currently Amended) The encapsulation as in ~~one of the preceding claims~~ claim 1, wherein said protective film includes a film made of silicon nitride.
6. (Currently Amended) The encapsulation as in ~~one of the preceding claims~~ claim 1, wherein said protective film includes a layer made of parylene C.
7. (Currently Amended) The encapsulation as in ~~one of the preceding claims~~ claim 1, wherein said protective film has a thickness in the range of 1 nm to 500 µm.

8. (Original) A method for producing an encapsulation, wherein an organic electronic component on a substrate is first covered with a capsule, the capsule is then fixed to the substrate, and the encapsulated component is thereafter covered at least in part with a protective film.

9. (Original) The method as in claim 8, wherein said capsule is glued to said substrate.

10. (Currently Amended) The method as in ~~either of claims~~ claim 8 or 9, wherein said protective film is applied to said encapsulated component by a method selected from the group including the following methods:

chemical vapor deposition, physical vapor deposition, wet chemical deposition, such as spin coating, dip coating, drop coating, printing techniques such as stencil printing, squeegee printing, screen printing, ink jet processes, spraying, plasma coating methods, plasma polymerization methods, laminating processes, hot sealing, transfer techniques (such as thermotransfer), welding methods and injection molding.

11. (Currently Amended) The method as in ~~one of claims~~ claim 8 to 10, wherein the application of the protective film takes place at least in part under reduced pressure.

12. (Currently Amended) The method as in ~~one of claims~~ claim 8 to 10, wherein the application of the protective film takes place at least in part in a high vacuum.

12. (Currently Amended) The method as in ~~one of claims~~ claim 8 to 11, wherein the protective film takes place at least in part via chemical vapor deposition. <sup>†</sup>

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<sup>†</sup>Translator's Note: Phraseology sic; repetition of claim number sic.

13. (Original) The method as in claim 12, wherein said chemical vapor deposition is plasma-assisted.
14. (Currently Amended) The method as in ~~one of claims~~ claim 8 to 13, wherein the contacting of the component by means of, inter alia, a connection cable bringing said organic electronic component into contact with an external drive or playback electronics and/or another type of connection (grounding) takes place prior to the application of said thin-barrier film protective film.
15. (Original) The use of an encapsulation according to ~~one of the preceding claims~~ claim 1 to protect organic electronic components, such as organic light-emitting diodes, polymer chips and/or organic photovoltaic and/or electrochromic elements and/or display applications that are organically based.